

APX003 is the first hybrid vision sensor designed for mobile photography applications, achieving outputs of frame-based image and novel event-based dynamic visual data in parallel. It offers an 8MP image resolution with a pixel size of only  $1.89\mu m \times 1.89\mu m$ . By incorporating event sensing technology with high temporal resolution, high dynamic range, and low data volume, APX003 significantly enhances high-speed motion estimation of devices under complex lighting conditions. It enables energy-efficient and superior-performanced imaging and vision applications, meeting the high-end demands in smartphones, action cameras, and consumer drones.

#### **Product Brief**

#### **EVS**

High frame rate

High SNR
High dynamic range
High sensitivity
Colored EVS
Superior low-light performance

#### **APS**

High quality image High-speed data output Rolling shutter

### **Features**

3D-stacked and BSI process
Output image and event data in parallel
8MP Image resolution
High infrared performance

## **Functions**

Support HDR
Configurable EVS contrast sensitivity and signal bandwidth
Configurable EVS data format
Independent ROI(APS&EVS)

Independent mirror and reverse

Independent mirror and reverse functions (APS&EVS)

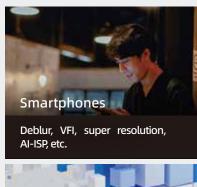
Support multi-camera data registration

# **Interface**

Data interface: MIPI D-PHY 4 Lane V1.2

Control interface: I<sup>2</sup>C & SPI

### **End products and Application**









Eye tracking and gesture recognition, 3D measurement





# **Key Specification**

Resolution	APS: 3264 × 2448 (8M)	ROI	Support(APS/EVS mode)
	EVS: 816 × 612 (0.5M)	Operating voltage	Analog: 3.0 V, 1.8 V
Pixel size	1.89 μm × 1.89 μm		Digital: 1.1 V
Optical format	½", CRA 34°		I/O: 1.8 V
Shutter mode	Rolling shutter	Imgae format	Raw12 / Raw10 / Raw8
EVS contrast sensitivity	/ Configurable 0 - 100%	Output interface	2 × 4 lane MIPI or,
Min. illumination	< 1 lux		1 × 4 lane MIPI with VC mode
Frame rate	APS: 30 fps @ Full Resolution	Dynamic range	APS: >60 dB
	EVS: 4000 fps @ Full Resolution		EVS: > 100 dB
Package	COB	Chip size	8.3mm × 6.9 mm
*Specs vary in different applications. Actual performance must b validated by customer's technical experts. Please contact us for more information.			

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